

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
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Property Type	Number
Application Number:	16749495
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DATE SIGNED:	07/20/2020
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ASSIGNMENT AND DECLARATION

WHEREAS, we:

<u>Inventor</u>	<u>Citizenship</u>	<u>Address</u>
Heiko SPECHT	DE	Am Wiesengrund 24 63456 Hanau Germany

(hereinafter referred to as "ASSIGNORS"), have made a discovery or invention ("INVENTION") entitled:

METHOD FOR MANUFACTURING A BIOCOMPATIBLE WIRE

- for which an application for Letters Patent of the United States has been executed on even date herewith,
- for which an application for Letters Patent of the United States has been filed on January 22, 2020, bearing Serial No. 16/749,495.

ASSIGNMENT

WHEREAS, at the time the INVENTION was made, ASSIGNORS were under an obligation to assign all rights, title, and interest in ASSIGNORS' INVENTION to:

Heraeus Deutschland GmbH & Co. KG
(a German Corporation)
Heraeusstrasse 12-14
63450 Hanau
Germany

and its legal representatives, successors, and assigns (hereinafter referred to as "ASSIGNEES"), which desires to formalize the assignment and its ownership of the entire interest in, to and under said INVENTION and in, to and under any and all applications for patent thereon and all Letters Patent which may be granted thereon.

NOW, THEREFORE, for valuable consideration received by ASSIGNORS, receipt and sufficiency of which is hereby acknowledged and agreed, and intending to be legally bound hereby, ASSIGNORS have assigned and hereby assign to ASSIGNEES, the entire right, title and interest to said INVENTION in the United States and its territorial possessions and in all foreign countries and to all Letters Patent or similar legal protection in the United States and its territorial possessions and in any and all foreign countries to be obtained for said INVENTION by said applications or any patent applications related thereto, including, but not limited to, continuations, divisionals, reexaminations or reissues thereof or any legal equivalent thereof in the United States and all foreign countries for the full term or terms for which the same may be granted.

WE, SAID ASSIGNORS, hereby covenant that we have full right to convey the entire right, title and interest herein to ASSIGNEE;

WE, SAID ASSIGNORS, hereby authorize ASSIGNEES, or its representatives, to insert the filing date and serial number of the application when these are known;

AND WE, SAID ASSIGNORS, hereby further covenant and agree that the ASSIGNEES may apply for foreign Letters Patent on said INVENTION, and that we will, at any time, when called upon to do so by the ASSIGNEES communicate to the ASSIGNEES as the case may be, any facts known to us respecting said INVENTION, and execute and deliver any and all lawful papers that may be necessary or desirable to perfect the title to the said INVENTION, the said applications and the said Letters Patent in the ASSIGNEES and that if reissues of the said Letters Patent or disclaimers relating thereto, or continuations, divisionals, reexaminations, or reissues of the said applications, or any thereof, shall hereafter be desired by the ASSIGNEES, we will, at any time, when requested by ASSIGNEES, sign all lawful papers, make all rightful oaths, execute and deliver all such disclaimers and all continuations, divisionals, reexaminations, or reissues of said applications so desired, and generally do everything possible to aid ASSIGNEES to obtain and enforce proper patent protection for said INVENTION, and without further compensation, but at the expense of the ASSIGNEES.

DECLARATION

As an above-named inventor, I hereby declare that:


This declaration is directed to the United States application referenced above.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention (or claimed design) in the above-identified application for which this declaration is being submitted.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Signature: <u></u>	Date: <u>Wannau, May 11, 2000</u>
Legal Name of Inventor: Heiko SPECHT	Citizenship: <u>DE</u>